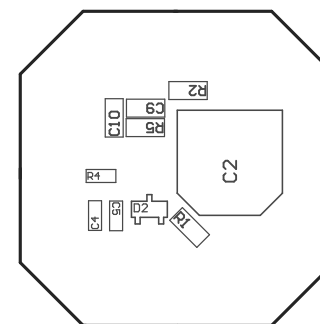


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01597	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01597		
PLOT NAME = Top Assembly Drawing	GENERATED : 2/28/2018 4:57:48 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01597	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01597		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/28/2018 4:57:53 PM		TEXAS INSTRUMENTS

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